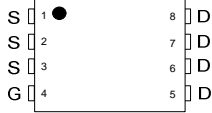
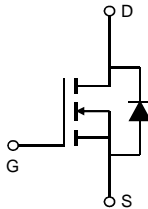


N-Channel Enhancement Mode Power MOSFET

<p><b>Features</b></p> <ul style="list-style-type: none"> <li>• 30V/30A</li> <li>• <math>R_{DS(ON)} = 7.5m\Omega(Typ.)@V_{GS}=10V</math></li> <li>• <math>R_{DS(ON)} = 9.3m\Omega(Typ.)@V_{GS}=4.5V</math></li> <li>• Super High Dense Cell Design</li> <li>• Fast Switching Speed</li> <li>• Low gate Charge</li> <li>• 100% avalanche tested</li> <li>• Lead Free and Green Devices Available</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Switching Application Systems</li> </ul>	 <p>PDFN 3333 top view</p>  <p>Schematic diagram</p>
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**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit
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**Common Ratings** ( $T_C=25^\circ C$  Unless Otherwise Noted)

$V_{DSS}$	Drain-Source Voltage	30	V	
$V_{GSS}$	Gate-Source Voltage	$\pm 20$		
$T_J$	Maximum Junction Temperature	150	$^\circ C$	
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$	
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ C$	30	A

**Mounted on Large Heat Sink**

$I_{DP}^{①}$	300 $\mu s$ Pulse Drain Current Tested	$T_C=25^\circ C$	100	A
$I_D^{②}$	Continuous Drain Current@ $T_C(V_{GS}=10V)$	$T_C=25^\circ C$	30	A
	Continuous Drain Current@ $T_A(V_{GS}=10V)^{③}$	$T_A=25^\circ C$	9.8	
$P_D$	Maximum Power Dissipation@ $T_C$	$T_C=25^\circ C$	30	W
	Maximum Power Dissipation@ $T_A^{③}$	$T_A=25^\circ C$	3.8	

Notes:

- ① Pulse width limited by safe operating area.
- ② Calculated continuous current based on maximum allowable junction temperature.
- ③ When mounted on 1 inch square copper board,  $t \leq 10sec$ .
- ④ Limited by  $T_{Jmax}$ ,  $I_{AS} = 13A$ ,  $V_{DD} = 24V$ ,  $R_G = 50\Omega$ , Starting  $T_J = 25^\circ C$ .
- ⑤ Pulse test; Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- ⑥ Guaranteed by design, not subject to production testing.



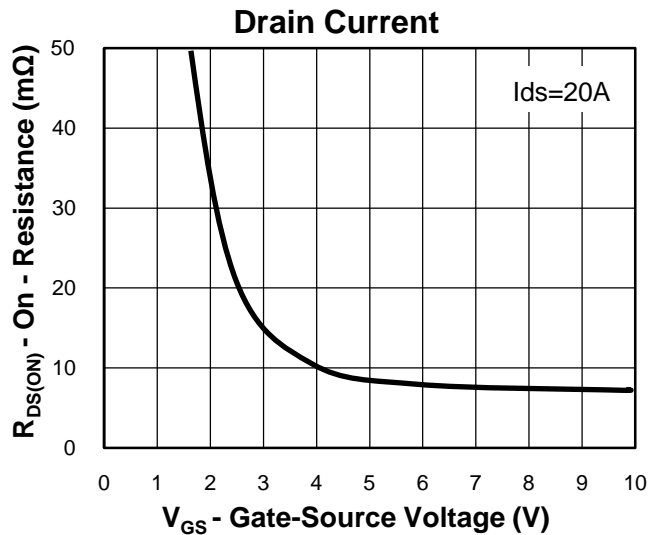
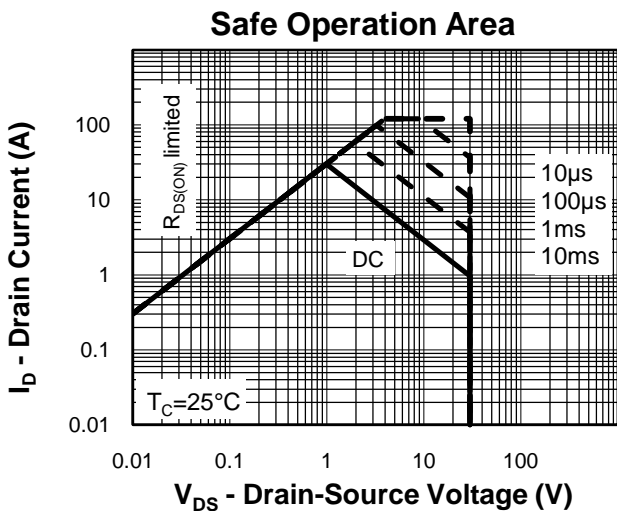
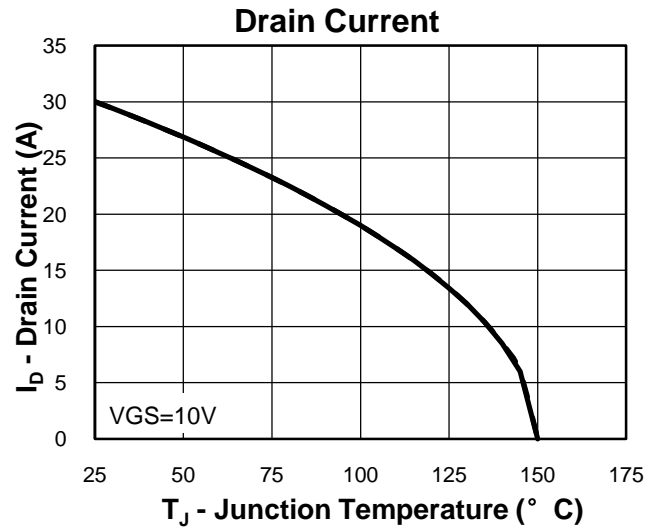
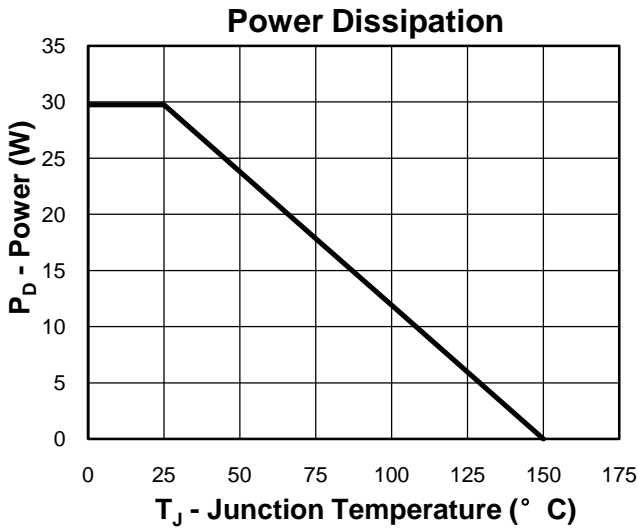
Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	4.5	°C/W
$R_{\theta JA}$ <sup>③</sup>	Thermal Resistance-Junction to Ambient	37	°C/W
<b>Drain-Source Avalanche Ratings</b>			
$E_{AS}$ <sup>④</sup>	Avalanche Energy, Single Pulsed	30	mJ

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  Unless Otherwise Noted)

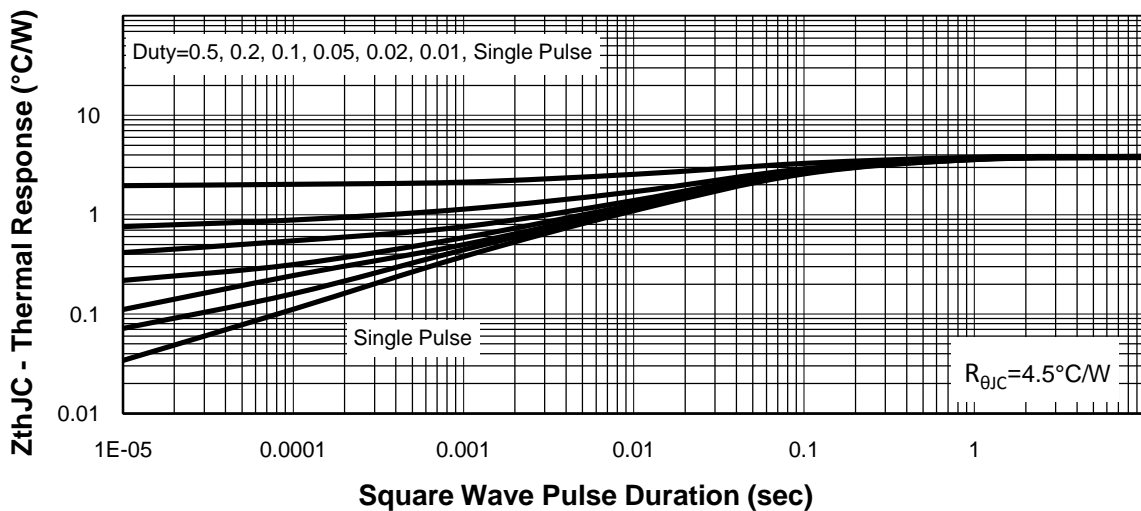
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$			1	$\mu A$
		$T_J=125^\circ\text{C}$			30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.2	1.4	2.2	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$R_{DS(ON)}$ <sup>⑤</sup>	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=20A$		7.5	9.0	m $\Omega$
		$V_{GS}=4.5V, I_{DS}=15A$		9.3	12	m $\Omega$
<b>Diode Characteristics</b>						
$V_{SD}$ <sup>⑤</sup>	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=0V$			1.2	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=20A, di_{SD}/dt=100A/\mu s$		13		ns
$Q_{rr}$	Reverse Recovery Charge			8		nC
<b>Dynamic Characteristics</b> <sup>⑥</sup>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$		1		$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=15V,$ Frequency=1.0MHz		1007		pF
$C_{oss}$	Output Capacitance			128		
$C_{riss}$	Reverse Transfer Capacitance			117		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=15V, R_L=0.75\Omega,$ $I_{DS}=20A, V_{GEN}=10V,$ $R_G=3\Omega$		5.7		ns
$t_r$	Turn-on Rise Time			47		
$t_{d(OFF)}$	Turn-off Delay Time			31		
$t_f$	Turn-off Fall Time			23		
<b>Gate Charge Characteristics</b> <sup>⑥</sup>						
$Q_g$	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V,$ $I_{DS}=20A$		23		nC
$Q_{gs}$	Gate-Source Charge			4.2		
$Q_{gd}$	Gate-Drain Charge			4.3		



Typical Characteristics

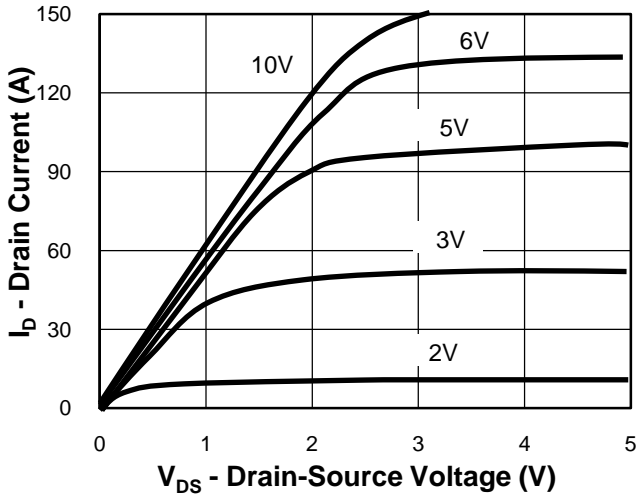


Thermal Transient Impedance

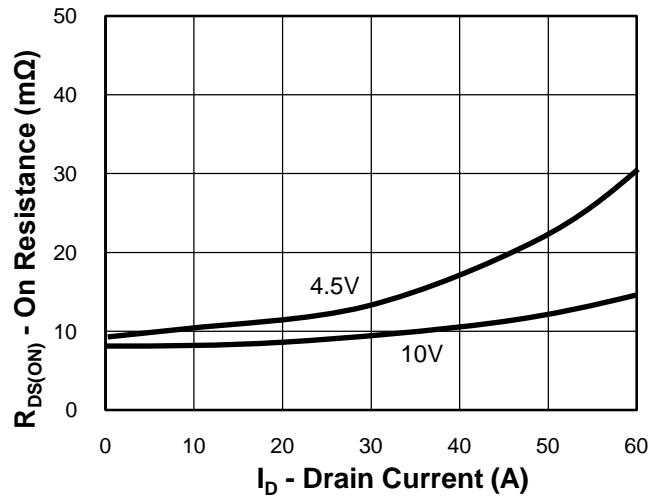


Typical Characteristics

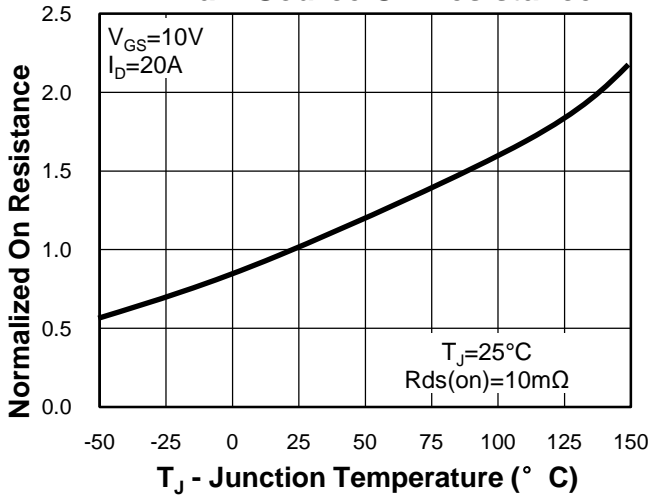
Output Characteristics



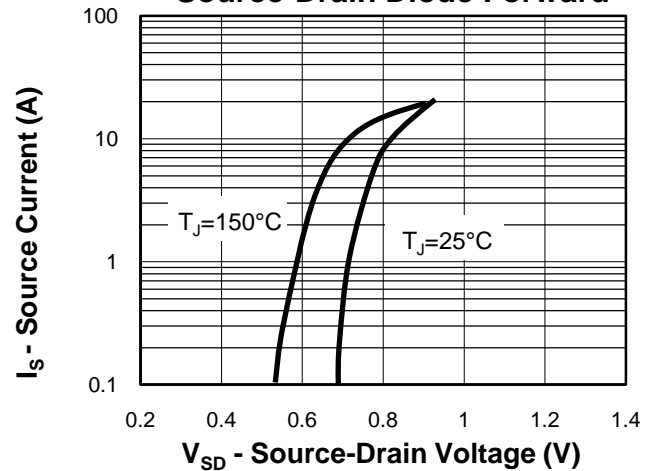
Drain-Source On Resistance



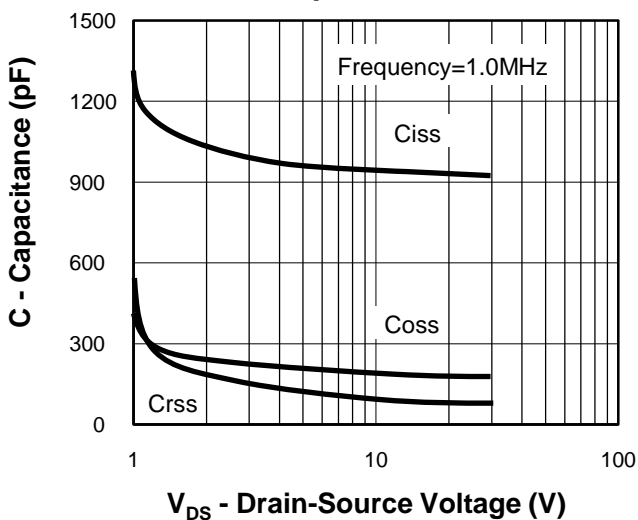
Drain-Source On Resistance



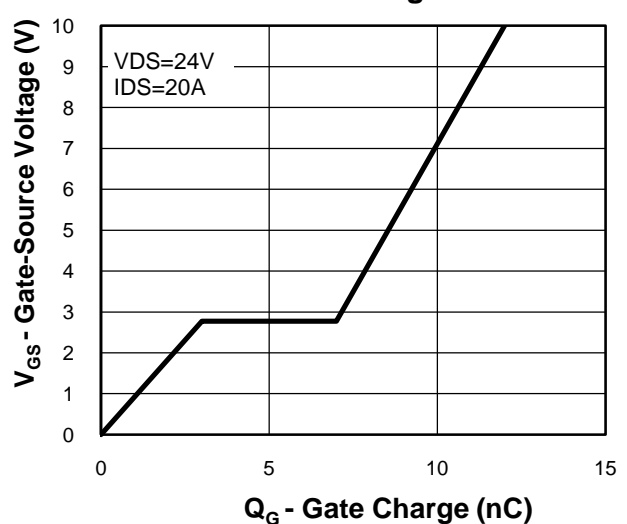
Source-Drain Diode Forward



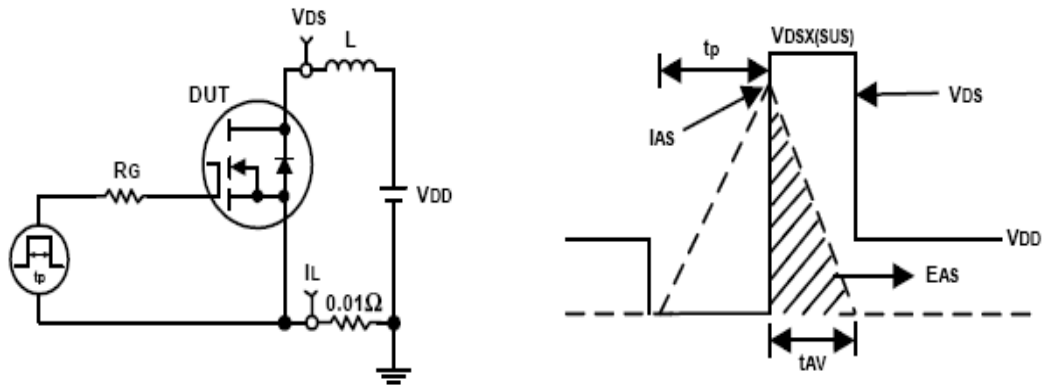
Capacitance



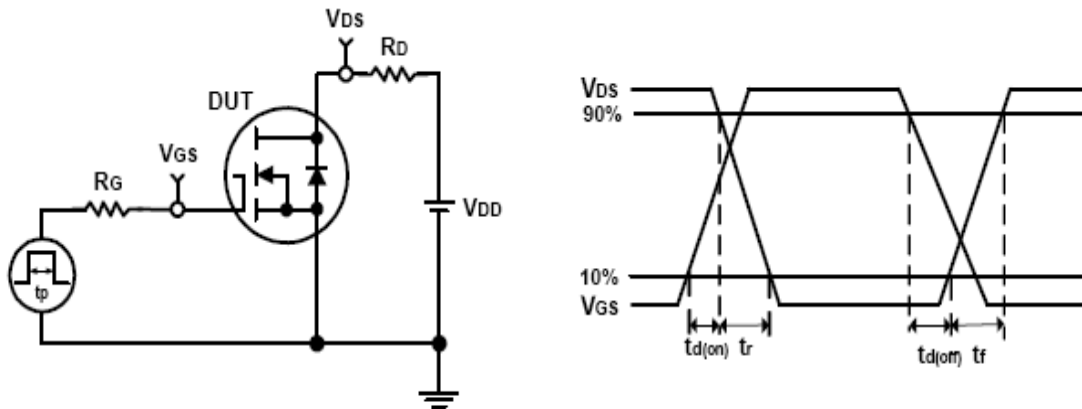
Gate Charge



### Avalanche Test Circuit and Waveforms

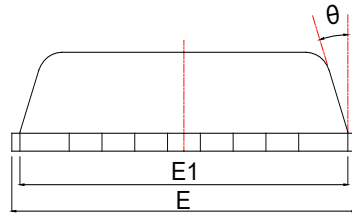
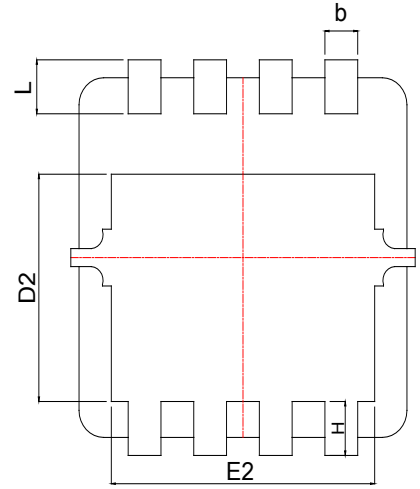
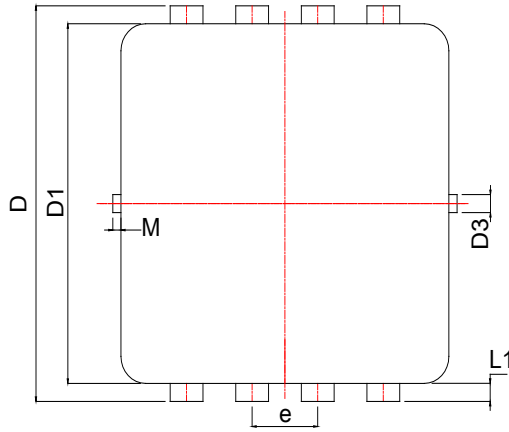
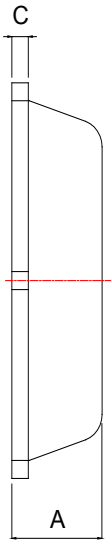


### Switching Time Test Circuit and Waveforms

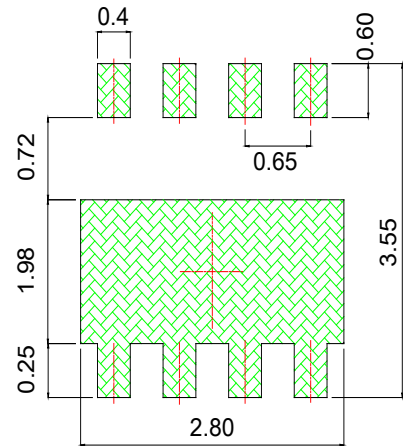


Package Information

PDFN3333



Land Pattern  
( Only for Reference )



SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031	E1	3.00	3.15	3.20	0.118	0.122	0.126
b	0.25	0.30	0.35	0.010	0.012	0.014	E2	2.39	2.49	2.59	0.094	0.098	0.102
c	0.10	0.15	0.25	0.004	0.007	0.010	e	0.65BSC			0.026BSC		
D	3.25	3.35	3.45	0.128	0.132	0.136	H	0.30	0.40	0.50	0.012	0.016	0.020
D1	3.00	3.10	3.20	0.118	0.122	0.126	L	0.30	0.40	0.50	0.012	0.016	0.020
D2	1.78	1.88	1.98	0.070	0.074	0.078	L1	*	0.13	*	*	0.005	*
D3	*	0.13	*	*	0.005	*	theta	*	10°	12°	*	10°	12°
E	3.20	3.30	3.40	0.126	0.130	0.134	M	*	*	0.15	*	*	0.006